

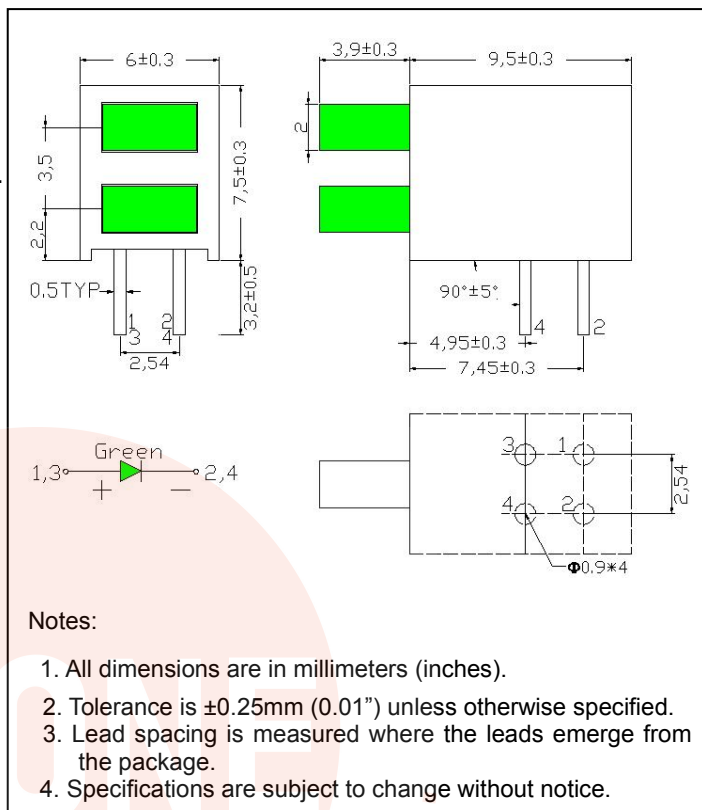
● Features:

1. Chip material:
2. Emitted color : Green
3. Lens Appearance :Green Diffused
4. Designed for ease in circuit board assembly.
5. Black case enhance contrast ratio.
6. Solid state light source.
7. Reliable and rugged.
8. This product don't contained restriction substance, compliance RoHS standard.

● Applications:

1. TV set
2. Monitor
3. Telephone
4. Computer
5. Circuit board

● Package dimensions



● Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Green	Unit
Power Dissipation	Pd	80	mW
Forward Current	I _F	20	mA
Peak Forward Current* ¹	I _{FP}	150	mA
Reverse Voltage	V _R	5	V
Operating Temperature	Topr	-40°C~80°C	
Storage Temperature	Tstg	-40°C~85°C	
Soldering Temperature	Tsol	260°C max (for 5 seconds)	
Hand Soldering Temperature	Tsol	350°C max(for 3 seconds)	

*¹Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

● Electrical and optical characteristics(Ta=25°C)

Parameter	Symbol	Condition	Color	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F=20\text{mA}$	Green	1.8	2.0	2.4	V
Luminous Intensity	I_v	$I_F=20\text{mA}$	Green	5	-	30	mcd
Reverse Current	I_R	$V_R=5\text{V}$	Green	-	-	10	μA
Peak Wave Length	λ_p	$I_F=20\text{mA}$	Green	-	-	-	nm
Dominant Wave Length	λ_d	$I_F=20\text{mA}$	Green	565	-	575	nm
Spectral Line Half-width	$\Delta\lambda$	$I_F=20\text{mA}$	Green	-	20	-	nm
Viewing Angle	$2\theta_{1/2}$	$I_F=20\text{mA}$	Green	-	60	-	deg

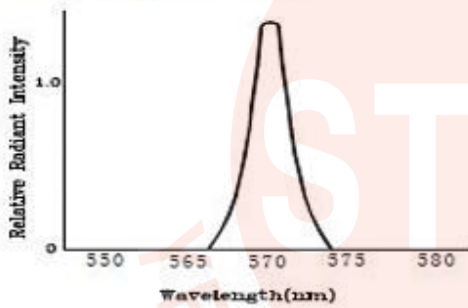
● Typical electro-optical characteristics curves

● Typical

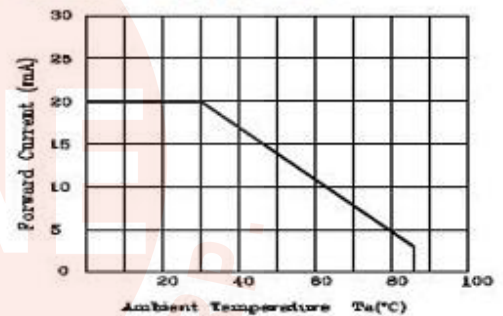
electro-optical

characteristics

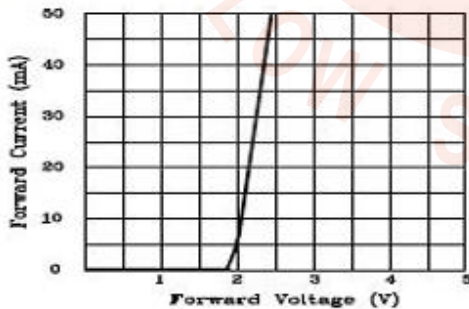
相对光谱分布特性曲线
Relative spectral emission



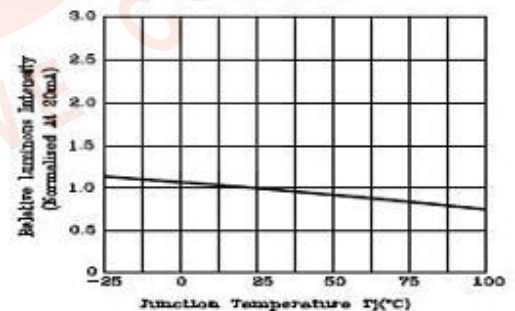
Ambient Temperature vs. Forward Current
环境温度与正向电流特性曲线



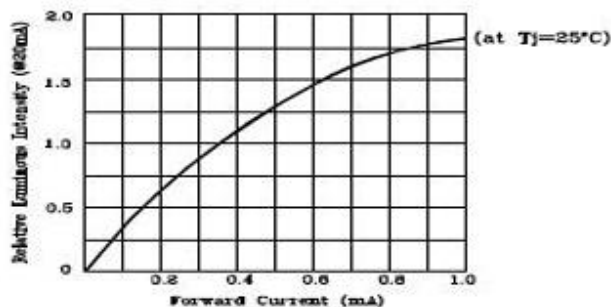
Forward Voltage VS. Forward Current
正向电压与正向电流特性曲线



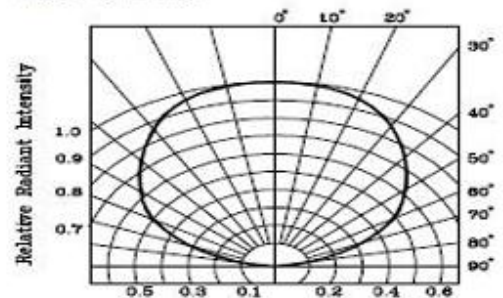
Ambient Temperature VS. Relative Intensity
环境温度与相对光强特性曲线



Forward Current VS. Relative Intensity
正向电流与相对光强特性曲线

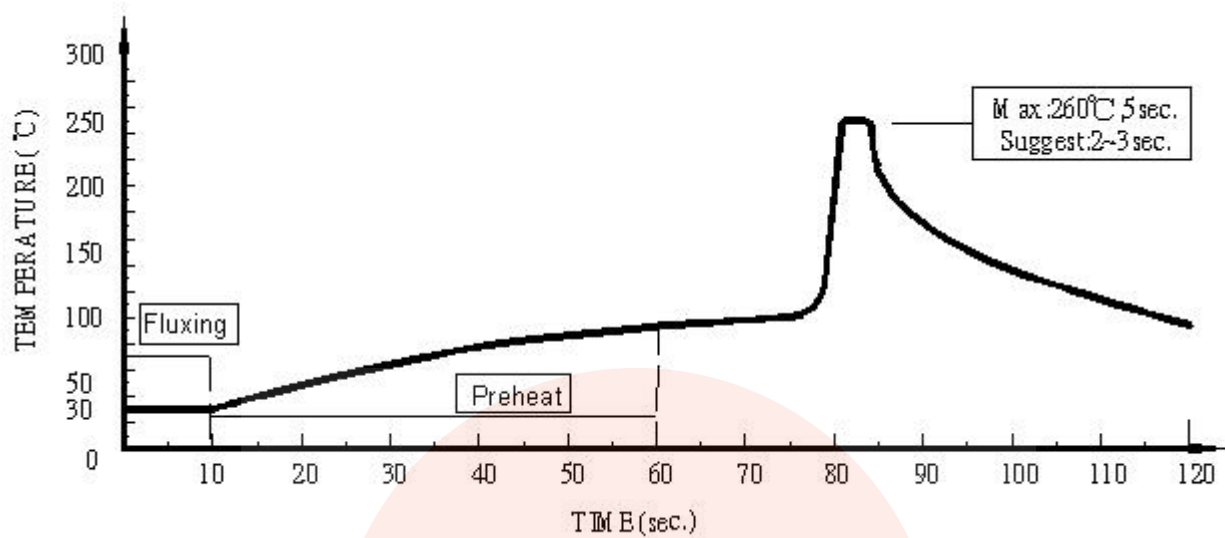


Radiation diagram
辐射图特性曲线



curves

● DIP Soldering



1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
2. DIP soldering and hand soldering should not be done more than one time.
3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temperature.
4. Avoid rapid cooling during temperature ramp-down process
5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

● IRON Soldering

A: Max: 350°C Within 3 sec. One time only.

B: The products of 3mm without flange, welding condition of flat plate PCB Max: 350°C

Within 2 sec. One time only

